

DSA 2023

Tenth International Conference on Dependable Systems and Their Applications Tokyo, Japan, August 10-11, 2023

In 2017, the International Conference on Trustworthy Systems and Their Applications (TSA) and the International Symposium on Dependable Computing and Internet of Things (DCIT) were merged into one large conference and renamed as the International Conference on Dependable Systems and Their Applications (DSA). This year will be the seventh meeting after the merge. In the past, both TSA and DCIT were technically sponsored by the IEEE Reliability Society. Following the same tradition, DSA 2023 also has the same technical sponsorship from IEEE. The focus is on innovative methodologies, techniques, tools, and management to produce dependable and trustworthy systems and their applications in a more cost-effective way. It provides an opportunity for academic researchers, industry practitioners, and government policy and decision makers to exchange ideas and results, share experiences, and explore possible solutions to overcome current challenges.

TOPICS OF INTEREST

- ◆ Algorithms, Architecture, Framework, Design Patterns, and Maintenance for Dependable Systems and Software
- ◆ Security, Threats, Privacy, Safety, and Risk Management
- ◆ Dependability and Reliability Modelling and Measurement
- ◆ Fault Tolerance, Survivability, Resilience, and Availability
- ◆ Metrics, Measurement, and Quality Assessment
- ◆ Requirements, Process, Standards, Productivity, and Project Management
- ◆ Quality Assurance, Maintenance, Reverse Engineering, and Re-Engineering
- ◆ Verification, Validation, Testing, Analysis, Debugging, Model Checking, and Program Repair
- ◆ Formal Methods and Theories
- ◆ Communication, Networking, Optimization, and Performance
- ◆ Pervasive, Ubiquitous, Service-Oriented, and Cloud Computing
- ◆ Collaborative, Distributed, Embedded, Real-Time, High Performance, Highly Dependable, Intelligent, Multimedia Systems
- ◆ Big Data and Storage
- ◆ Prognostics and Health Management
- ◆ IoT, Supply Chain, Cyber-Physical Systems, Industry 4.0, and Smart City
- ◆ Empirical Studies, Benchmarking, and Industrial Best Practices
- ◆ Applications and Tools and Automation
- ◆ Approaching Artificial Creativity

IMPORTANT DATES

- ◆ May 25, 2023 Regular & Short Papers due
- ◆ June 1, 2023 Workshop Papers due
- ◆ June 1, 2023 Fast Abstracts & Industry Track due
- ◆ July 10, 2023 Author notification
- ◆ July 20, 2023 Camera-ready and copyright due
- ◆ July 20, 2023 Author registration due
- ◆ August 10 - 11, 2023 Conference dates

SUBMISSION

There are five types of submissions:

- ◆ Regular Paper 12 pages
- ◆ Short Paper 10 pages
- ◆ Industry Track 2 pages
- ◆ Fast Abstract 2 pages
- ◆ Workshop Paper 10 pages

Submit original papers (not published or submitted elsewhere). Each submission must include the title of the paper, the name and affiliation of each author, and up to 6 keywords. Regular, short, and workshop papers should also have a 150-word abstract. All papers should be written in English and submitted as a PDF file. Authors must follow the required [DSA proceedings format](https://dsa23.techconf.org/proceedings-format). At least one Best Paper Award will be presented. Detailed instructions for paper submission can be found at <https://dsa23.techconf.org/submission>

CONFERENCE PROCEEDINGS & SCI JOURNAL PUBLICATION

The conference proceedings will be published by the IEEE Conference Publishing Services (CPS). Papers presented at the conference will also be submitted for inclusion into the IEEE Xplore and to all of the A&I (abstracting and indexing) partners (such as the Ei Compendex and DBLP). Authors of top quality papers will be invited to submit their extended versions to a special issue of a selected SCI journal.

ORGANIZING COMMITTEE

- ◆ General Chair Hironori Washizaki Waseda University, Japan
- ◆ General Chair Gordon Fraser University of Passau, Germany
- ◆ Program Chair Rui Maranhão University of Porto, Portugal
- ◆ Program Chair Ying Qian Chongqing University of Posts and Telecommunications, China

GENERAL INQUIRIES

For more detailed and updated information, please refer to <https://dsa.techconf.org/> or send emails to [DSA Secretariat](mailto:dsa@techconf.org).